

20V N-Channel Enhancement Mode MOSFET

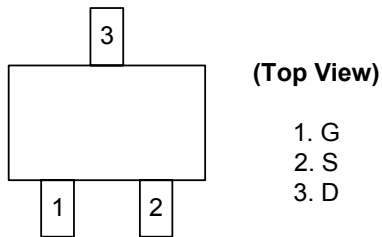
■ Features

- Advanced trench process technology
- High density cell design for ultra low on-resistance
- Excellent thermal and electrical capabilities
- Compact and low profile SOT-23 package

■ Product Summary

$V_{DS} = 20V$
 $R_{DS(on)}, V_{GS}@4.5V, I_{DS}@3.6A} = 65m\Omega$.
 $R_{DS(on)}, V_{GS}@2.5V, I_{DS}@3.1A} = 95m\Omega$.

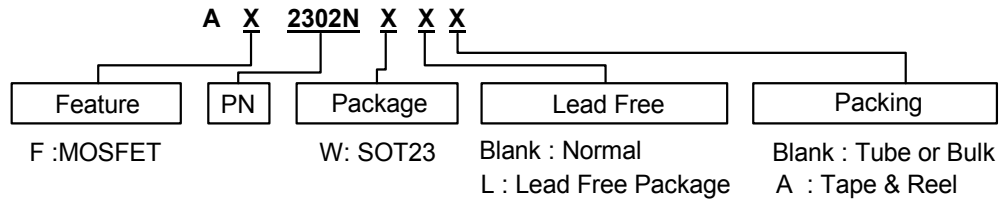
■ Pin Assignments



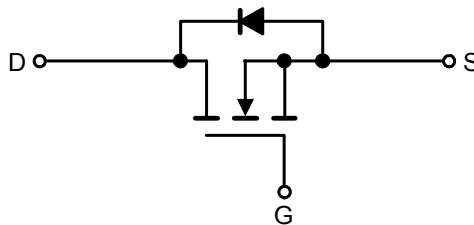
■ Pin Descriptions

Pin No.	Pin Name	Description
1	G	Gate
2	S	Source
3	D	Drain

■ Ordering information



■ Block Diagram





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■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 8	V
I_D	Continuous Drain Current	2.4	A
I_{DM}	Pulsed Drain Current	10	A
P_D	Maximum Power Dissipation	$T_A=25^\circ\text{C}$	1.25
		$T_A=70^\circ\text{C}$	0.8
T_J	Operating Junction Temperature	+150	$^\circ\text{C}$
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$

■ Thermal Performance

Symbol	Parameter	Limit	Units
T_L	Lead Temperature (1/8" from case)	5	S
$R_{\theta JA}$	Junction to Ambient Thermal Resistance (PCB mounted)	100	$^\circ\text{C/W}$

Note: Surface mounted on FR4 board $t \leq 5$ sec.

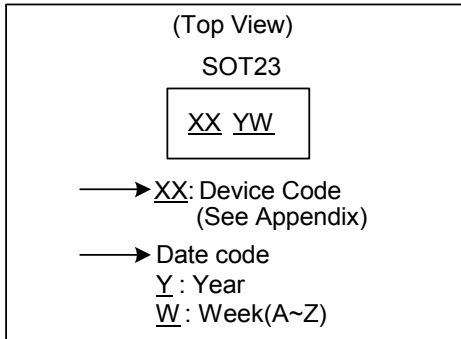
■ Electrical Characteristics Rate $I_D=2.4\text{A}$, ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Limits			Unit
			Min.	Typ.	Max.	
Static						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	20	-	-	V
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS}=4.5\text{V}, I_D=3.6\text{A}$	-	50	65	m Ω
		$V_{GS}=2.5\text{V}, I_D=3.1\text{A}$	-	75	95	
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.45	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}, V_{GS}=0\text{V}$	-	-	1.0	μA
I_{GSS}	Gate Body Leakage	$V_{GS}=\pm 8\text{V}, V_{DS}=0\text{V}$	-	-	± 100	nA
$I_{D(ON)}$	On-State Drain Current	$V_{DS}=5\text{V}, V_{GS}=4.5\text{V}$	6	-	-	A
g_{fs}	Forward Transconductance	$V_{DS}=5\text{V}, I_D=3.6\text{A}$	-	10	-	S
Dynamic						
Q_g	Total Gate Charge	$V_{DS}=10\text{V}, I_D=3.6\text{A},$ $V_{GS}=4.5\text{V}$	-	5.2	10	nC
Q_{gs}	Gate-Source Charge		-	0.65	-	
Q_{gd}	Gate-Drain Charge		-	1.5	-	
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=10\text{V}, R_L=10\Omega,$ $I_D=1\text{A}, V_{GEN}=4.5\text{V},$ $R_G=6\Omega$	-	7	15	nS
t_r	Turn-On Rise Time		-	55	80	
$t_{d(off)}$	Turn-Off Delay Time		-	16	60	
t_f	Turn-Off Fall-Time		-	10	25	
C_{iss}	Input Capacitance	$V_{DS}=10\text{V}, V_{GS}=0\text{V},$ $f=1.0\text{MHz}$	-	450	-	pF
C_{oss}	Output Capacitance		-	70	-	
C_{riss}	Reverse Transfer Capacitance		-	43	-	
Source-Drain Diode						
I_S	Max. Diode Forward Current		-	-	1.6	A
V_{SD}	Diode Forward Voltage	$I_S=1.0\text{A}, V_{GS}=0\text{V}$	-	0.75	1.2	V

Note: Pulse test: pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$

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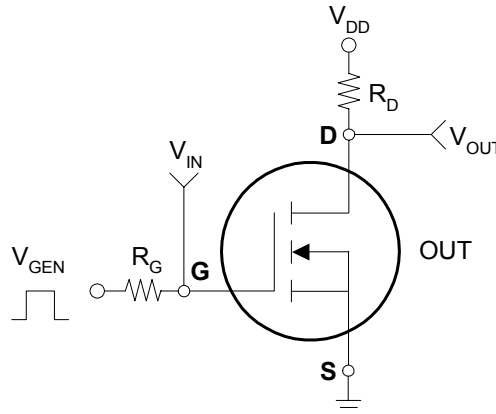
■ Marking Information



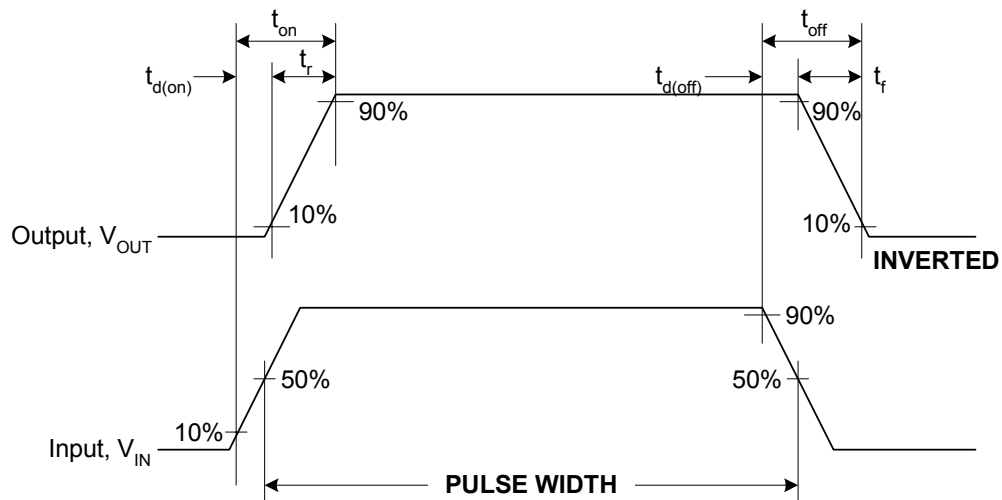
Appendix

Part Number	Package	Device Code
AF2302N	SOT23-3	02

■ Switching Test Circuit

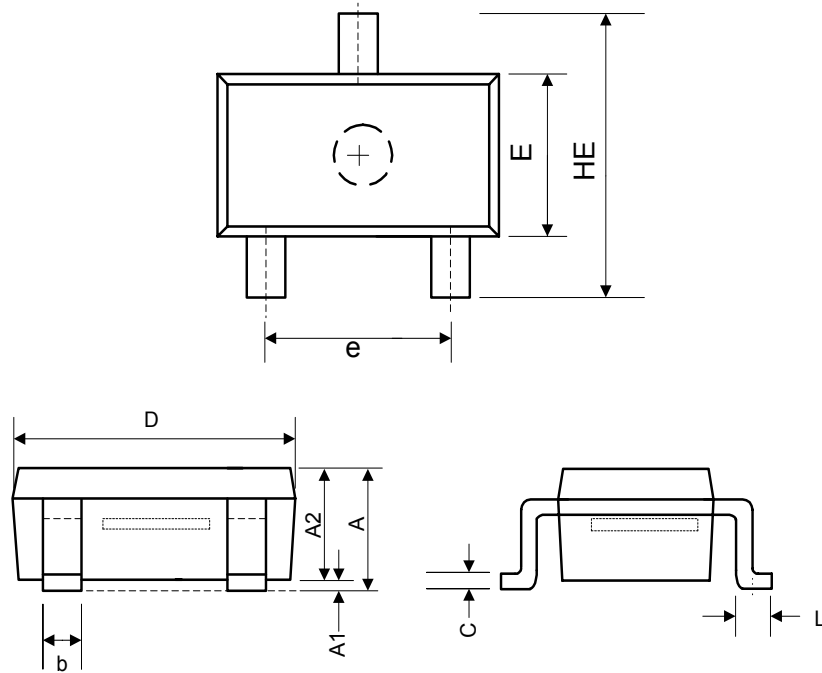


■ Switching Waveforms



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■ Package Information



Symbol	Dimensions In Millimeters			Dimensions In Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	1.00	1.20	1.40	0.039	0.047	0.055
A1	0.00	-	0.10	0.000	-	0.004
A2	1.00	1.15	1.30	0.039	0.045	0.051
b	0.35	-	0.50	0.014	-	0.020
C	0.10	0.175	0.25	0.004	0.007	0.010
D	2.70	2.90	3.10	0.106	0.114	0.122
E	1.40	1.60	1.80	0.055	0.063	0.071
e	1.70	2.00	2.30	0.067	0.079	0.091
HE	2.40	2.70	3.00	0.094	0.106	0.118
L	0.30	-	0.55	0.012	-	0.022